

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Houston
Serial No.: TBD
Filed: 07/01/99
For: **BONDED SOI WITH BURIED INTERCONNECT TO HANDLE OR
DEVICE WAFER**

Docket No.: TI-21004
Examiner: TBD
Art Unit: TBD

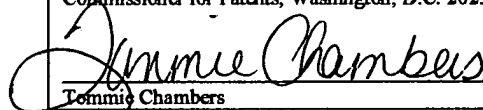
PRELIMINARY AMENDMENT

Assistant Commissioner
for Patents
Washington DC 20231

Dear Sir:

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(a)

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231 on:

 7-1-99
Tommie Chambers Date

Please amend the above referenced Application as follows:

In the Specification:


Page 1, before line 1, insert --This application claims priority under 35 USC §119(e)(1)
of provisional application number 60/095,293 filed 08/04/98.--

REMARKS

Entry of the foregoing amendment prior to examinations is respectfully requested.

If the Examiner has any questions or other correspondence regarding this application, Applicant requests that the Examiner contact Applicant's attorney at the below listed telephone number and address.

Respectfully submitted,


Jacqueline J. Garner
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